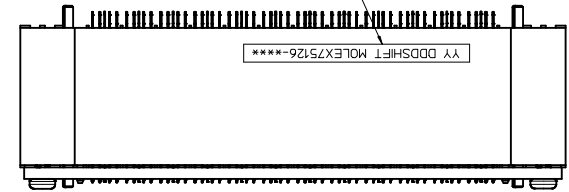


DATE CODE, MOLEX, PART NUMBER



NOTES:

1. MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94V-0.
WAFER DIELECTRIC: LIQUID CRYSTAL POLYMER (LCP), 94V-0, BLACK.
CONTACTS: COPPER ALLOY
HEXAGONAL MACHINE SCREW: CARBON STEEL
2. THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
3. THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
4. THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC PS-45499-002.
5. RECOMMENDED DRILL SIZE: 0.61±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
6. USE APPLICATION TOOL 622020232 WHEN INSERTING INTO PCB.
7. RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THICKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

CONVERT TO LEAD-FREE EEC NO: UCP2013-1884 DRAWN BY: IBARRA CHYK: 2012/11/12 APPR: MILLER 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	
	▽=0	4 PLACES ± --- ± ---	DATE	TITLE		
	▽=0	3 PLACES ± --- ± .010	02/06/27	PLATEAU HS DOCK INTERPOSER SALES DRAWING		
	2 PLACES ± 0.25 ± ---	DATE	DATE			
	1 PLACE ± --- ± ---	DATE	DATE			
	0 PLACE ± ±	DATE	DATE			
	ANGULAR ± 2 °	MATERIAL NO.	DOCUMENT NO.			SHEET NO.
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	SD-75126-001			1 OF 3
		SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

CIRCUIT SIZE	ITEM NUMBER	HS DOCK CONNECTOR	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	PLATING OPTION	CONNECTOR WAFER TYPE
108			90.50 3.563	81.50 3.209	89.00 3.504	75.62 2.977	99.40 3.913	71.00±0.08 2.795±.003	66.00±0.08 2.598±.003	FINISH 1	WELDED
144	75126-1003	75018-3021	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-1103	75018-3121	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 2	
144	75126-3003	75018-3121	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-7103	75018-8121	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 3	

1. PLATING FINISH:

FINISH 1: (PREVIOUSLY TIN-LEAD)

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD

NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER

NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER

COPPER UNDERPLATE OVERALL

FINISH 2:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD

NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER

NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER

COPPER UNDERPLATE OVERALL

FINISH 3:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD

NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER

NICKEL UNDERPLATE OVERALL

HOUSING

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER

COPPER UNDERPLATE OVERALL

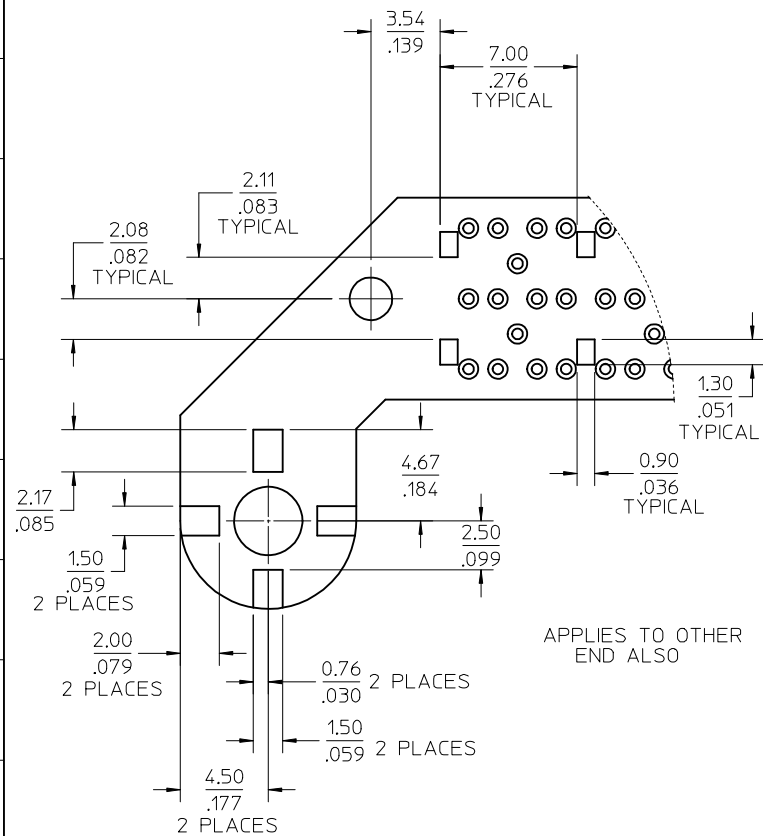
SEE SHEET 1 EC NO: UCP2013-1884 DRAWN BY: JORDWNTIBARRA CHKD: APPRS: MILLER REV: 2012/11/12 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ±.010	MM/IN	2:1	METRIC	
	▽=0	3 PLACES ±.010				
	▽=0	2 PLACES ±0.25				
		1 PLACE ±.010				
		0 PLACE ±				
		ANGULAR ± 2 °				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
			MATERIAL NO.	DOCUMENT NO.		
			SEE TABLE	SD-75126-001		
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
						SHEET NO. 2 OF 3

PLATEAU HS DOCK INTERPOSER SALES DRAWING

molex

SD-75126-001

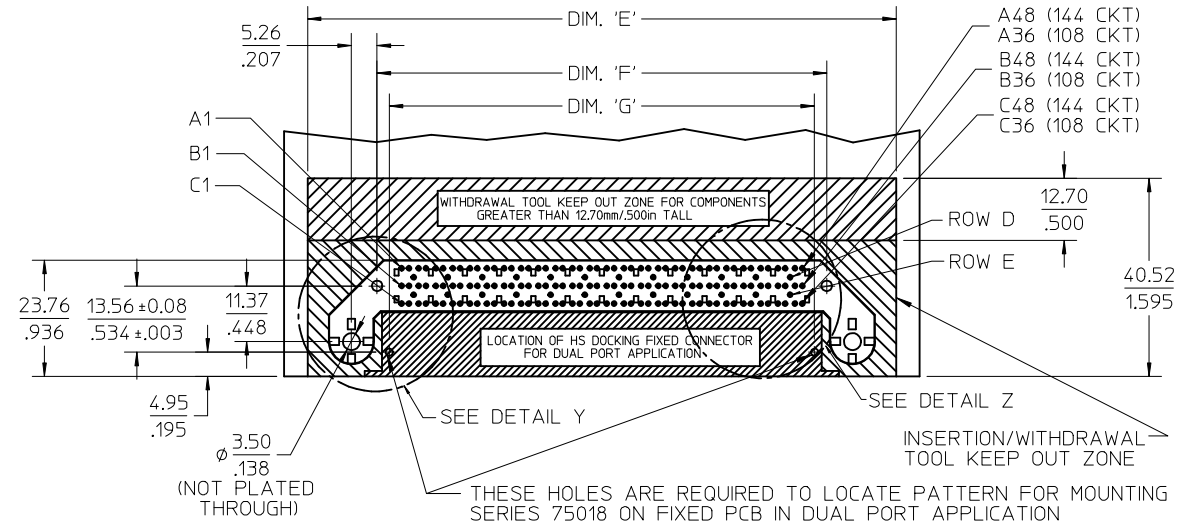
KEEP OUT AREA FOR CONNECTOR STAND-OFFS



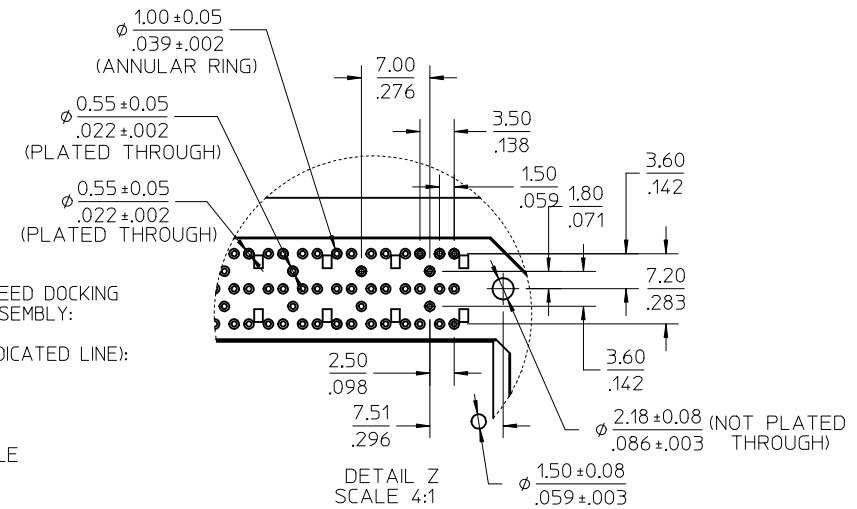
DETAIL Y
SCALE 8:1

NOTE: THE DIMENSION DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO



THESE HOLES ARE REQUIRED TO LOCATE PATTERN FOR MOUNTING SERIES 75018 ON FIXED PCB IN DUAL PORT APPLICATION



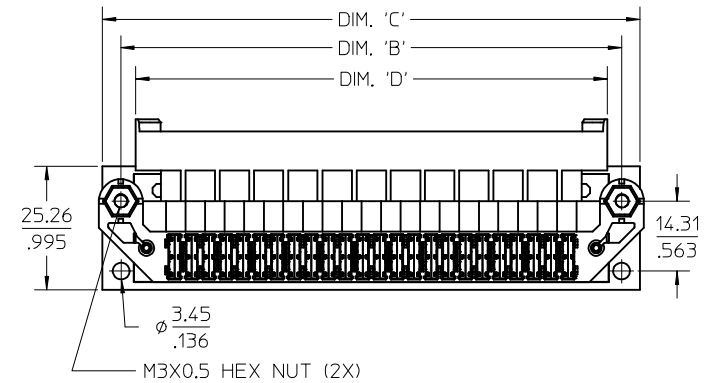
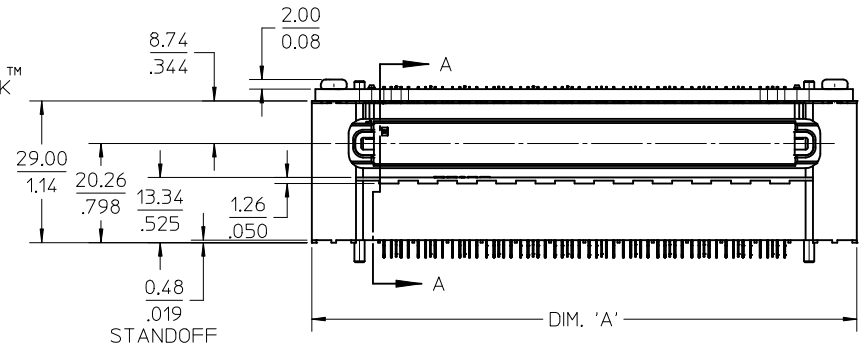
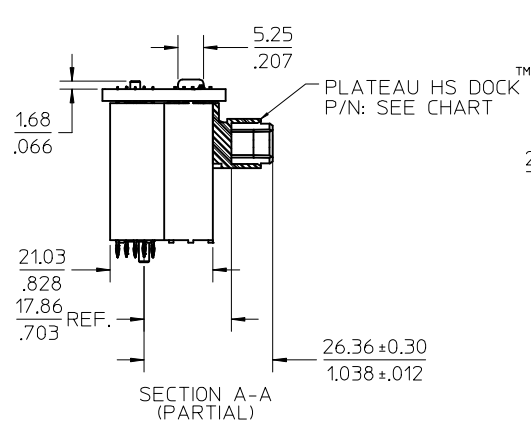
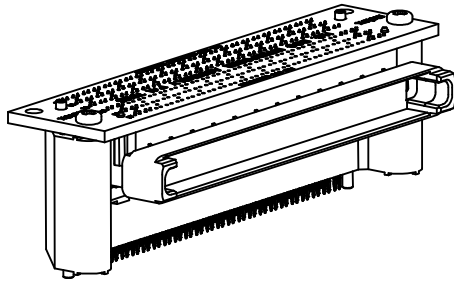
CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:

POWER CIRCUITS (15 AMPS PER INDICATED LINE):
A2-A1: POWER/RETURN;
A4-A3: POWER/RETURN;
C2-C1: POWER/RETURN

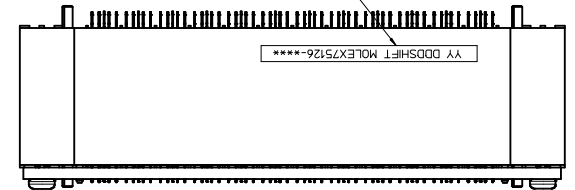
ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS
CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E

SEE SHEET 1 EC NO: UCP2013-1884 DRAWN: IBARRA 2012/11/12 CHKD: APPR: SKILLER 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	1:1	METRIC	☉
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
	▽=0	3 PLACES ± --- ± .010	DSCMIDG 02/06/12	PLATEAU HS DOCK INTERPOSER SALES DRAWING		
	2 PLACES ± 0.25 ± ---	CHECKED BY DATE	DOCUMENT NO.			SHEET NO.
	1 PLACE ± --- ± ---	DSCMIDG 2003/03/18	SD-75126-001			3 OF 3
	0 PLACE ± ±	APPROVED BY DATE	MATERIAL NO.			
		MBANKIS 2/18/03	SEE TABLE			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			
			SIZE D THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



DATE CODE, MOLEX, PART NUMBER



NOTES:

1. MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94 V-0.
WAFER: LIQUID CRYSTAL POLYMER (LCP), 94 V-0, BLACK.
CONTACTS: COPPER ALLOY
HEXAGONAL THREADED INSERT: CARBON STEEL
MACHINE SCREW: CARBON STEEL
2. THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
3. THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
4. THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC. PS-45499-002.
5. RECOMMENDED DRILL SIZE: 0.66±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
6. USE APPLICATION TOOL 62202XXXX WHEN INSERTING INTO PCB.
7. RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THCKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

CONVERT TO LEAD-FREE EC NO: UCP2013-1884 2012/11/12 DRAWN BY: J BARRA CHKD: J BARRA APPR: MILLER 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	⊙
	▽=0	4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- 0 PLACE ± ±	DRAWN BY: KSTILES DATE: 7/16/2003 CHECKED BY: DATE: 7/16/2003 APPROVED BY: DATE: 7/16/2003 MBANKIS	TITLE	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
	▽=0	ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	DOCUMENT NO.	SD-75126-002 SHEET NO. 1 OF 3	
MATERIAL NO. SD-75126-002 SIZE D THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

CIRCUIT SIZE	ITEM NUMBER	PLATEAU HS DOCK™	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	PLATING FINISH	CONNECTOR WAFER TYPE
108			90.50 3.563	81.50 3.209	89.00 3.504	75.62 2.977	99.40 3.913	71.00±0.08 2.795±.003	66.00±0.08 2.598±.003	FINISH 1	WELDED
144	75126-2001	75018-3023	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-2101	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 2	
144	75126-4001	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-8101	75018-8123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 3	

1. PLATING FINISH:

FINISH 1: (PREVIOUSLY TIN-LEAD)

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
COPPER UNDERPLATE OVERALL

FINISH 2:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
COPPER UNDERPLATE OVERALL

FINISH 3:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
NICKEL UNDERPLATE OVERALL

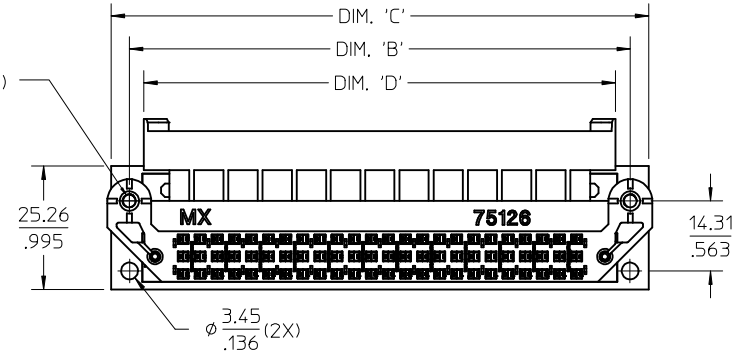
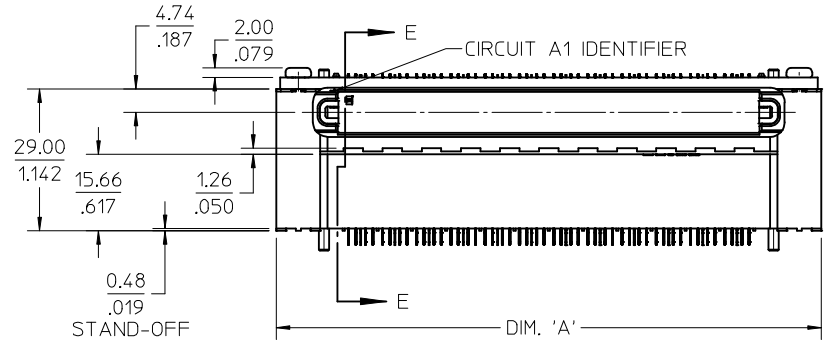
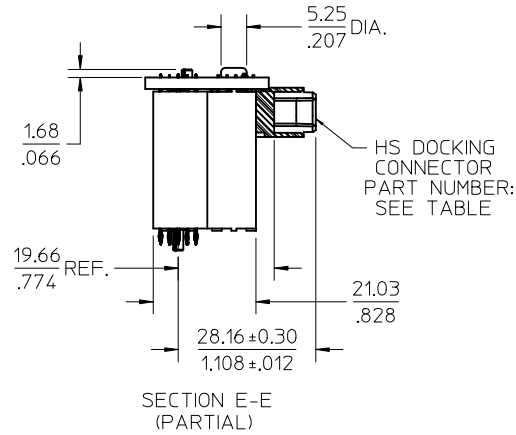
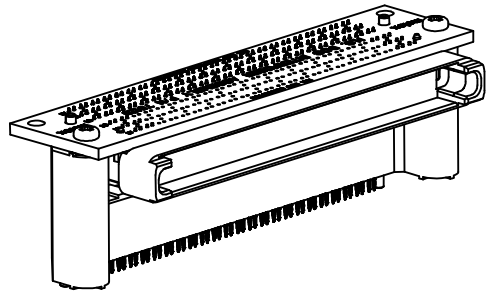
COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
NICKEL UNDERPLATE OVERALL

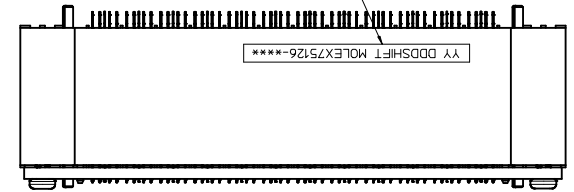
HOUSING

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
COPPER UNDERPLATE OVERALL

SEE SHEET 1 EEC NO: UCP2013-1884 DRAWN BY: J. BARRA CHKD: J. BARRA APPR: MILLER 2012/11/12 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ±.010	MM/IN	2:1	METRIC	
	▽=0	3 PLACES ±.025				
	▽=0	2 PLACES ±.050				
		ANGULAR ±1/2°				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
			DRAWN BY: KSTILES	DATE: 7/16/2003	TITLE: PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
			CHECKED BY: DSCHMIDG	DATE: 7/16/2003	molex	
			APPROVED BY: MBANKIS	DATE: 7/16/2003	DOCUMENT NO. SD-75126-002	
			MATERIAL NO.	DATE	SHEET NO. 2 OF 3	
			SIZE: D	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



DATE CODE, MOLEX, PART NUMBER



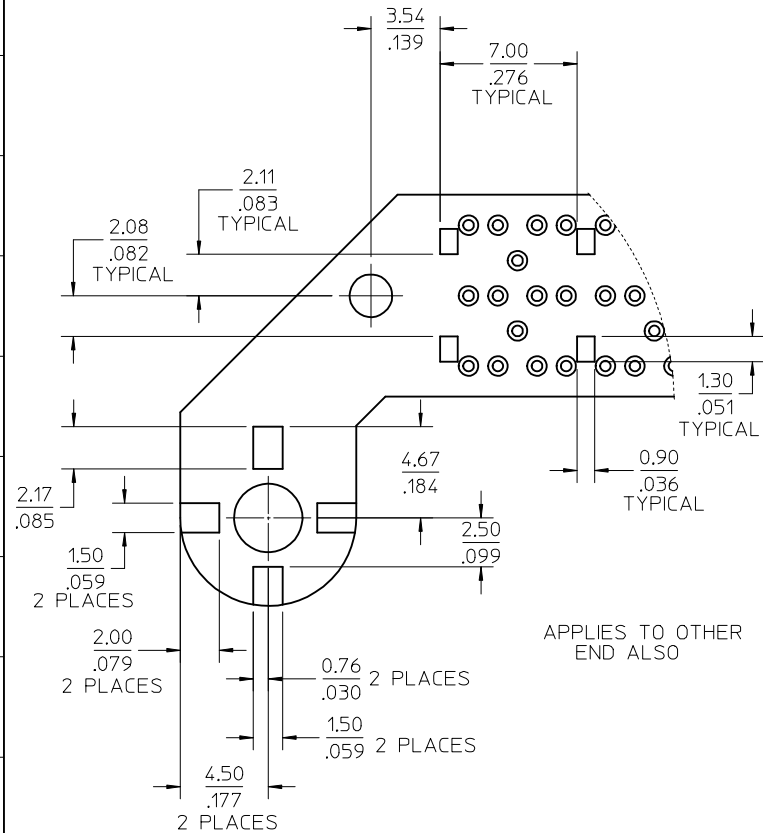
CIRCUIT SIZE	ITEM NUMBER	HS DOCK CONNECTOR	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	CONNECTOR WAFER TYPE
144	75126-7303	75018-5121	<u>111.50</u> 4.390	<u>102.50</u> 4.035	<u>110.00</u> 4.331	<u>96.62</u> 3.804	<u>120.40</u> 4.740	<u>92.00±0.08</u> 3.622±.003	<u>87.00±0.08</u> 3.425±.003	WELDLESS

NOTES:

- MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94V-0.
WAFER DIELECTRIC: LIQUID CRYSTAL POLYMER (LCP), 94V-0, BLACK.
CONTACTS: COPPER ALLOY
HEXAGONAL THREADED INSERT: CARBON STEEL
MACHINE SCREW: CARBON STEEL
- PLATING FINISH:
CONTACT INTERFACE
0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
NICKEL UNDERPLATE OVERALL
COMPLIANT INTERFACE
0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
NICKEL UNDERPLATE OVERALL
HOUSING
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
COPPER UNDERPLATE OVERALL
- THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
- THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
- THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC PS-45499-002.
- RECOMMENDED DRILL SIZE: 0.61±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
- USE APPLICATION TOOL 622020232 WHEN INSERTING INTO PCB.
- RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THICKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN, 5 IN-LBS MAX.

INITIAL RELEASE EC NO: UCP2014-3379 DRAWN BY: IBARRA 2014/02/13 CHKD BY: BBARKER 2014/02/14 APPR: SMILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▽=0	mm INCH	MM/IN	2:1	METRIC		
	▽=0	4 PLACES ± --- ± ---					
	▽=0	3 PLACES ± --- ± .010					
		2 PLACES ± 0.25 ± ---					
		1 PLACE ± --- ± ---					
		0 PLACE ± ±					
		ANGULAR ± 2 °					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					
		MATERIAL NO.	DATE	TITLE			
		SEE TABLE	2014/02/13	PLATEAU HS DOCK INTERPOSER SALES DRAWING			
		DATE	2014/02/14				
		APPROVED BY	DATE				
		SMILLER	2014/03/13				
		DOCUMENT NO.					
		SD-75126-1000					
		SHEET NO.					
		1 OF 2					
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

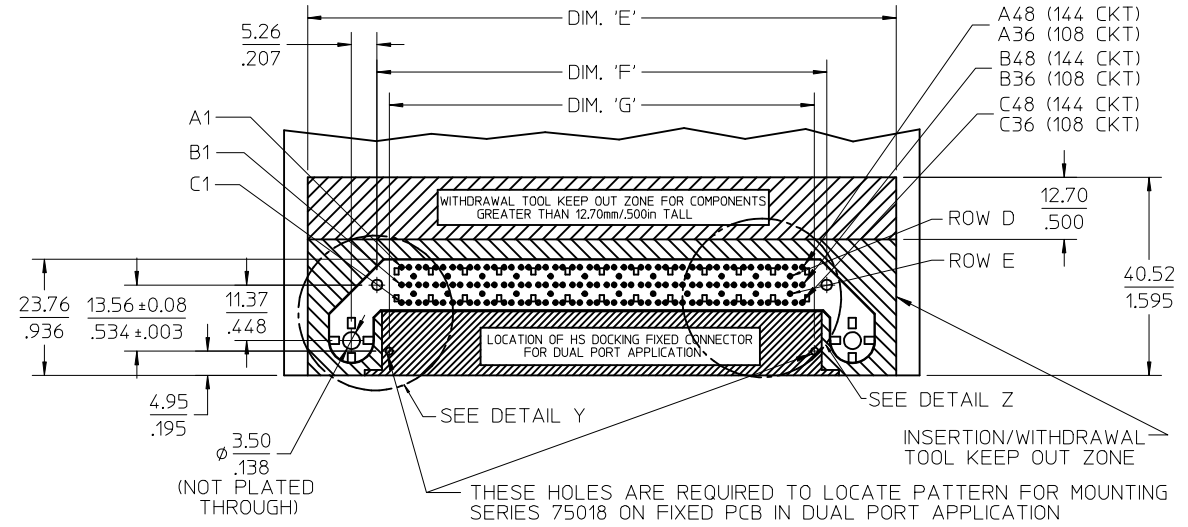
KEEP OUT AREA FOR CONNECTOR STAND-OFFS



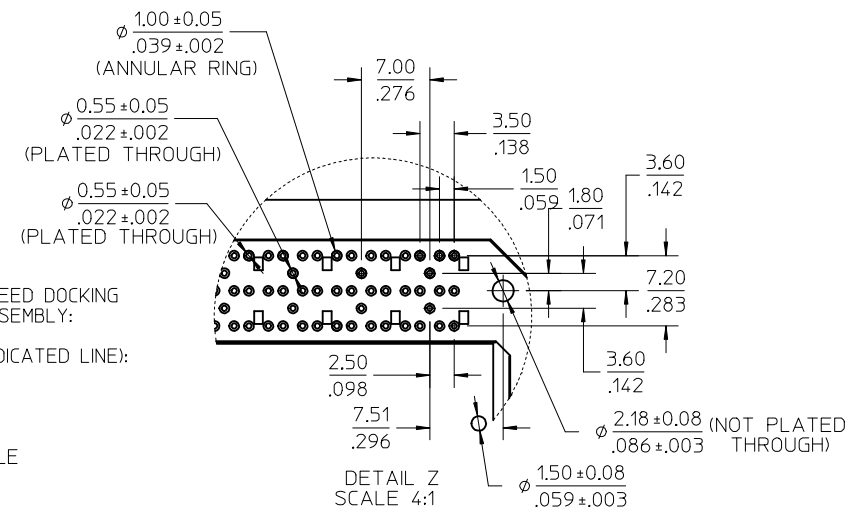
DETAIL Y
SCALE 8:1

NOTE: THE DIMENSION DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO



THESE HOLES ARE REQUIRED TO LOCATE PATTERN FOR MOUNTING SERIES 75018 ON FIXED PCB IN DUAL PORT APPLICATION



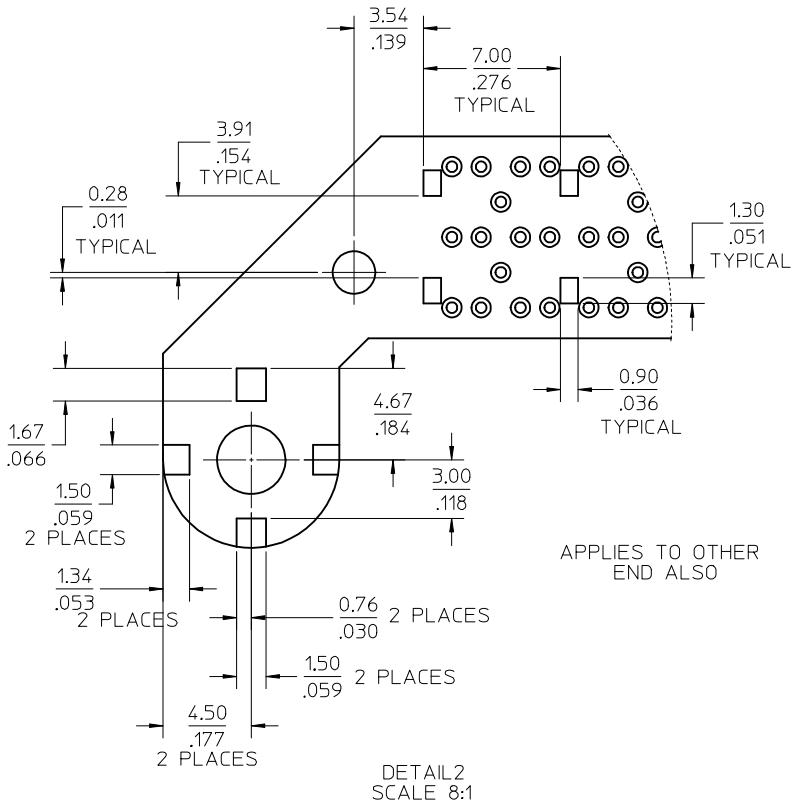
CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:
 POWER CIRCUITS (15 AMPS PER INDICATED LINE):
 A2-A1: POWER/RETURN;
 A4-A3: POWER/RETURN;
 C2-C1: POWER/RETURN

ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS
 CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E

SEE SHEET 1 IEC NO: UCP2014-3379 DRAWN BY: TIBARRA 2014/02/13 CHECKED BY: CHYKOBARKER 2014/02/14 APPROVED BY: SMILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	1:1	METRIC	☉
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TIBARRA 2014/02/13	TITLE	
	▽=0	3 PLACES ± --- ± .010	CHECKED BY DATE	BBARKER 2014/02/14	PLATEAU HS DOCK INTERPOSER SALES DRAWING	
	1 PLACE ± --- ± ---	APPROVED BY DATE	SMILLER 2014/03/13	DOCUMENT NO.		SHEET NO.
	0 PLACE ± --- ± ---	ANGULAR ± 2 °	MATERIAL NO.	SD-75126-1000		2 OF 2
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

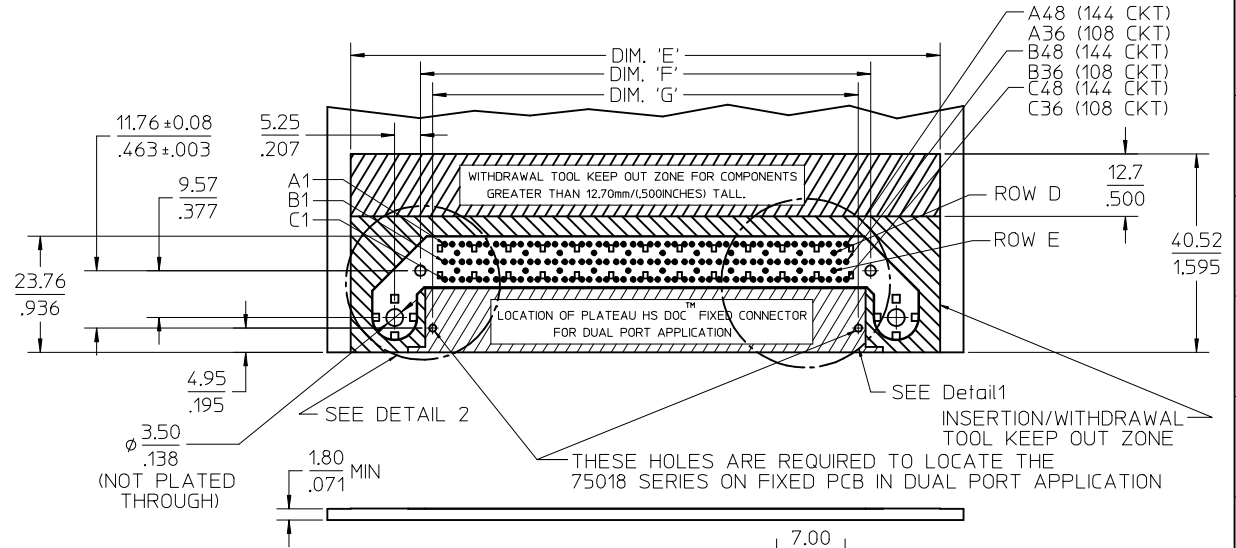
KEEP OUT AREA FOR STAND-OFFS



DETAIL2
SCALE 8:1

NOTE: THE DIMENSIONS DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO

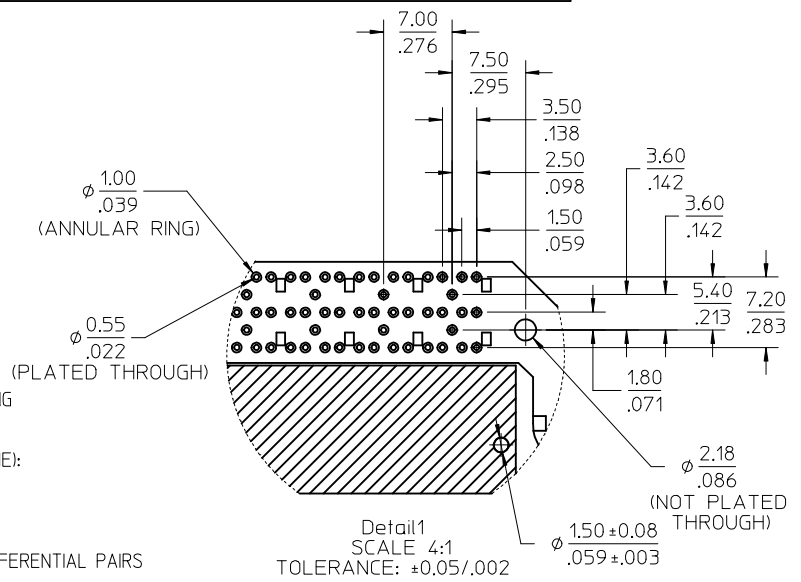


CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:

POWER CIRCUITS (15 AMPS PER INDICATED LINE):
A2-A1: POWER/RETURN,
A4-A3: POWER/RETURN,
C2-C1: POWER/RETURN

ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS
CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E



Detail1
SCALE 4:1

TOLERANCE: ±0.05/.002

SEE SHEET 1 EC NO: UCP2014-3379 DRAWN: T. BARRA 2014/02/13 CHKD: B. BARKER 2014/02/14 APPR: S. MILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	☉
	▽=0	4 PLACES ± .010	DATE	DATE	TITLE	
	▽=0	3 PLACES ± .025	T. BARRA 2014/02/13	B. BARKER 2014/02/14	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
	1 PLACE ± .050	APPROVED BY	DATE	DOCUMENT NO.		SHEET NO.
	0 PLACE ± .050	S. MILLER 2014/03/13	DATE	SD-75126-2000		2 OF 2
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		